



Layer	Stack up	Description	Copper Layer Type	Base Thickness	Processed Thickness	Resin Content	εr	Loss Tangent	Impedance ID
1		LPI Mask			25.400		4.000	0.0000	
		Copper Foil	Signal	18.000	18.000				
2		PrePreg 1651		150.000	150.000	47.000	4.200	0.0195	
		PrePreg 1651		150.000	150.000	47.000	4.200	0.0195	
3		FR4 Core	Plane	35.000	35.000				
		FR4 Core	Signal	300.000	300.000	46.000	4.200	0.0195	
4		PrePreg 1080		65.670	65.670	60.000	4.200	0.0195	
		PrePreg 106		50.000	50.000	60.000	4.200	0.0195	
5		PrePreg 1080		65.670	65.670	60.000	4.200	0.0195	
		FR4 Core	Signal	35.000	35.000				
6		FR4 Core	Plane	300.000	300.000	46.000	4.200	0.0195	
		FR4 Core	Signal	35.000	35.000				
		PrePreg 1651		150.000	150.000	47.000	4.200	0.0195	
		PrePreg 1651		150.000	150.000	47.000	4.200	0.0195	
		Copper Foil	Signal	18.000	18.000				
		LPI Mask			25.400		4.000	0.0000	

Copper Thickness = 176.000 | Dielectric Thickness = 1381.340 | Solder Mask Thickness = 50.800 | Stack Up Thickness = 1557.340 | Stack Up Thickness with Soldermask = 1608.140
 Stack Up Cost = 41.50

Drill Image	1st Layer	2nd Layer	Column Position	Drill Type
	1	6	1	Mechanical PTH

Supplier	Supplier Description	Description	Type	Stock Number	Stack Quantity	Unit Cost	Stack Cost	Total Quantity	Total Cost
Polar Samples	SM/001	LPI Mask	SolderMask	500-001	2	0.50	1.00	2	1.00
Polar Samples	FO/001	Copper Foil	Copper	100-001	2	1.00	2.00	2	2.00
Polar Samples	PP/004	PrePreg 1651	Dielectric	300-004	4	1.00	4.00	4	4.00
Polar Samples	CO/020	FR4 Core	FR4	400-020	2	2.00	4.00	2	4.00
Polar Samples	PP/001	PrePreg 1080	Dielectric	300-001	2	1.00	2.00	2	2.00
Polar Samples	PP/006	PrePreg 106	Dielectric	300-006	1	2.00	2.00	1	2.00
							15.00		15.00

No. of Panels = 1 | Circuits Per Panel = 1 | Price Per Circuit = 15.00 |

Notes

StackName: Master	Version:	Revision:	Modification:	Date of Revision:	Editor
Date:	Associated Documents:				
Author:					
Department:					
Site:					

